## **KEMET Surface Mount Tantalum**

Revision K, 11 March 2013

<u>Note</u>: Information subject to change without notice. Monitor website regularly for updates. KEMET is not liable for any damages, direct or indirect, consequential or otherwise, that the reader might incur as a result of ignoring this warning, or that any third party might suffer as a result of the reader's ignoring this warning.



Tape & Reel Packaging

Graphite / Silver

**RoHS Restricted Substance Content** 

Tantalum

Key for Determining Adherence to China RoHS and EU 2011/65/EU Content Criteria<sup>1</sup> O = ≤ MCV, X = > MCV, X = > MCV, but EU RoHS Compliant with Exemption(s)

			Restricted Material						Compliant Version		
		Matavial						Compliant Version			
		Material and MCV <sup>1</sup>	Cd	Cr <sup>6+</sup>	Pb	Hg	PBB	PBDE	Available	Standard	China RoHS
KEMET Product	Series	Termination Code	< 0.01%	< 0.1%	< 0.1%	< 0.1%	< 0.1%	< 0.1%	since	since	Symbol <sup>4</sup>
Precision Molded Chip	T491	T or G T or B	ο	0	ο	ο	ο	ο	Mar-00	n/a - Termination unique for Pb-Free	0
Low ESR, Industrial Grade	T494										
Low ESR, Surge Robust	T495										
Fail Safe Fused	T496		0	0	ο	ο	ο	ο	Varies <sup>2</sup>	Varies <sup>2</sup>	0
High Grade COTS	T497										
High Temperature Tantalum	T498, T499										
Ultra-Low ESR	T510										
Multi Anode COTS	T513										
Precision Molded Chip	T491	H	0	ο	x	ο	ο	ο			
Low ESR, Industrial Grade	T494										0
Low ESR, Surge Robust	T495										
Fail Safe Fused	T496										
High Grade COTS	T497										
High Temperature Tantalum	T498, T499										
Ultra-Low ESR	T510										1
Multi Anode COTS	T513										
Style CWR11 per MIL-PRF-55365/8	T492	S	0	0	Х	0	0	0			6
		G	0	0	0	0	0	0	Mar-00	n/a - Termination unique for Pb-Free	0
	T409 (CWR09), T419 (CWR19), T429 (CWR29)	В	0	0	0	0	0	0	May-06	n/a - Termination unique for Pb-Free	0
		Solder options per catalog	ο	0	х	0	0	ο			0
Commercial-Off-The-Shelf (COTS)	T493	T or B	0	0	0	0	0	0	Oct-05	n/a - Termination unique for Pb-Free	0
		Solder options per catalog	0	0	X	0	0	0			8

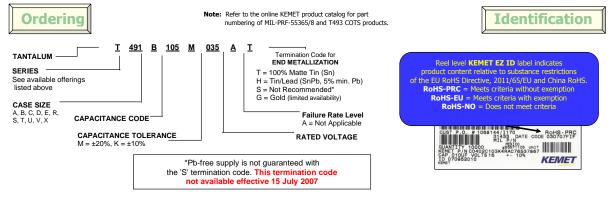
<sup>2</sup>Consult the Tantalum Lead-Free Conversion Schedule for clean date KEMET converted to Pb-Free as standard manufacturing by series and case size.

<sup>4</sup>China RoHS Symbol based on current manufacturing. Refer to notes in Pb column for transition dates

## Soldering Capability Characteristics

	Matte Tin Termination	SnPb Termination		
Termination Material	Copper	Copper		
Termination Plating (Barrier)	100% Matte Tin (Copper, Nickel)	90Sn10Pb (Copper)		
Peak Temperature Capability	260°C	260°C		
Soldering Process Compatibility	Backward & Forward Compatible	Backward & Forward Compatible		
MSL Rating	1	1		
Tin Whisker Test Results	Class 2	Class 2		
based on JESD22-A121 and JESD201 <sup>5</sup>				

<sup>5</sup>Per EIA/ECA component bulletin CB19, tin whiskering is not considered a reliability risk within the capacitor industry for non-Military / Hi-Rel applications.



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